

PDX181

INDENTED BILL OF MATERIALS  
 DATES: ALL

BY COMPONENT ID

ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM	ABC	COMM	CLASS	TYPE	ST	PLNR	BUYER	MRP	MPS	YIELD
						EFF	DATE	PENDING	CATG	TOTAL	REQD	BILL	OPER	KIT	LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
			2		00040					QTY:		1				
1.....	01016863	0002 PC CARD MODULE (MERLIN CDPD OEM)				EA			M	A	EP		0		0	0.0
			1		00040							1.000000				
.2.....	01016632	0006 PCB MSCH. ASSY (MERLIN)				EA			M	A	EP		0		0	0.0
			2		00044							1.000000				
.3.....	01016582	0001 PCB ASSY PCMCIA CARD (MERLIN)				EA			M	A	EP		0		0	0.0
			3									1.000000				
...4.....	01016603	0001 FLASH ASSY INCLUDING BOOTLOADER (MERLIN)				EA			M	A	EP		0		0	0.0
			1									1.000000				
....5.....	20416383	0002 SW, HEX FILE, MERLIN-EMLV, TRL-07				EA			B	A	EP		0		0	0.0
		TRLO										1.000000				
....5.....	31323916	0006 IC 29LV200BT FLASH 90 NS (TSOP-48)				EA			B	A	EP		0		0	0.0
												1.000000				
		REF: U101														
....5.....	DF-01016603	0002 FLASH ASSY INCLUDING BOOTLOADER (MERLIN)				EA			P	A	EP		0		0	0.0
			1									0.000000				
....5.....	SWI-20416383	0004 SW WORK INSTRUCTIONS HEX FILE TRL-07				EA			P	A	EP		0		0	0.0
												0.000000				
...4.....	01016742	0002 LABEL SERIAL NUMBER PCB ASSY				EA			M	A	EP		0		0	0.0
			1									1.000000				
....5.....	25015458	0006 LABEL BLANK KEYED 12.2MM X 12.2MM				EA			B	A	EP		0		0	0.0
			1									1.000000				
....5.....	32123001	0010 RIBBON PRINTER RESIN 60MM X 450M				MM			B	A	EP		0		0	0.0
												15.200000				
....5.....	DA-01016742	0002 LABEL SERIAL NUMBER PCB ASSY				EA			P	A	EP		0		0	0.0
			1									0.000000				
....5.....	DM-25015458	0008 LABEL BLNK KEYED 12.2MM X 12.2MM				EA			P	A	EP		0		0	0.0
			1									0.000000				

















POKIBL

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ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM EFP	ABC DATE	COMM PENDING	CLASS CATG	TYPE TOTAL	ST REQD	PLNR BILL	BUYER OPER	MRP KIT	MPS LTO	YIELD SCRAP
ASM: 649496	00265 7	MERLIN CDPD ORM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
			2		00040					QTY:		1				
...4.....	18523192	0053 INDUCTOR CHIP 5.6NH 5% 0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L225										1.000000				
...4.....	18523194	0055 INDUCTOR CHIP 47NH 5% 0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L220										1.000000				
...4.....	18523196	0057 INDUCTOR CHIP 12NH 5%0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L204										3.000000				
		REF: L209														
		REF: L215														
...4.....	18523198	0059 INDUCTOR CHIP 100UH SHIELDED 3% 1210				EA				B	A	EP	0		0	0.0
		REF: L224										1.000000				
...4.....	18523200	0061 INDUCTOR CHIP 100NH 5% 0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L218										3.000000				
		REF: L226														
		REF: L227														
...4.....	18523201	0062 INDUCTOR CHIP 6.8NH 5% 0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L201										2.000000				
		REF: L203														
...4.....	18523202	0063 INDUCTOR CHIP 15NH 5% 0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L200										2.000000				
		REF: L211														
...4.....	18523204	0064 INDUCTOR CHIP 33NH 3% 0805 PTL2012				EA				B	A	EP	0		0	0.0
		REF: L208										1.000000				
...4.....	18523206	0065 INDUCTOR CHIP 27NH 5% 0603 LL1608				EA				B	A	EP	0		0	0.0
		REF: L202										1.000000				



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ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM EFF DATE	ABC PENDING	COMM CATG	CLASS	TYPE	QT TOTAL	PLNR REQD	BUYER BILL	MRP OPER	MPS KIT	YIELD LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)		2	00040	EA C	6494			M	A			Y	N	0.0	
										QTY:		1					
...4.....	27023092	0080 FILTER CERAMIC 450 KHZ LOW PROFILE				EA				B	A	EP	0			0	0.0
		REF: CF201										2.000000					
		REF: CF200															
...4.....	27023093	0081 FILTER SAW LIL 869-894 MHZ				EA				B	A	EP	0			0	0.0
		REF: FL200										1.000000					
...4.....	27023094	0082 FILTER SAW LIL 824-849 MHZ				EA				B	A	EP	0			0	0.0
		REF: FL201										1.000000					
...4.....	31323679	0083 IC TA31132FN FM DEMODULATOR(SSOP24)				EA				B	A	EP	0			0	0.0
		REF: U211										1.000000					
...4.....	31323680	0084 IC TC4866F BI SWITCH ANALOG (SSOP5)				EA				B	A	EP	0			0	0.0
		REF: U215										1.000000					
...4.....	31323853	0085 IC MX589 GMSK MODEM (TSSOP-24)				EA				B	A	EP	0			0	0.0
		REF: U301										1.000000					
...4.....	31323872	0087 IC LMX1601 DUAL PLL (16-PIN TSSOP				EA				B	A	EP	0			0	0.0
		REF: U210										1.000000					
...4.....	31323873	0088 IC LMV822 8-PIN MSOP OP-AMP DUAL				EA				B	A	EP	0			0	0.0
		REF: U204										2.000000					
		REF: U302															
...4.....	31323874	0089 IC UPC2771TB MED PWR SI MMIC AMP SOT-363				EA				B	A	EP	0			0	0.0
		REF: U206										1.000000					
...4.....	31323876	0090 IC UPC8106TB UPCONVERTER SOT363				EA				B	A	EP	0			0	0.0
		REF: U207										1.000000					

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ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	RCN	UM EFF DATE	ABC PENDING	COMM CATG	CLASS	TYPE	QT TOTAL	PLNR REQD	BUYER BILL	MRP OPER	MPS KIT	YIELD LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)		2	00040	EA	C	6494		M	A			Y	N	0.0	
										QTY:		1					
...4.....	31323880	0091 IC AM186EM CPU 25MHZ 3.3V (TQFP-100)				EA				B	A	EP	0		0	0.0	
		REF: U100										1.000000					
...4.....	31323885	0093 IC MAX 1111 ADC 8 BIT 4CH (QSOP-16)				EA				B	A	EP	0		0	0.0	
		REF: U304										1.000000					
...4.....	31323890	0094 IC TQ9223C LNA DOWNCONVERTER				EA				B	A	EP	0		0	0.0	
		REF: U202										1.000000					
...4.....	31323891	0095 IC FMM5512ZE PA 800MHZ GAAS (SSOP-16)				EA				B	A	EP	0		0	0.0	
		REF: U205										1.000000					
...4.....	31323893	0097 IC DIGITAL POT 100K QUAD (TSOP-24)				EA				B	A	EP	0		0	0.0	
		REF: U300										1.000000					
...4.....	31323895	0098 IC MIC5205 3.0V REGULATOR (SOT-23-5)				EA				B	A	EP	0		0	0.0	
		REF: U212										3.000000					
		REF: U213															
		REF: U303															
...4.....	31323897	0100 IC MMIC 1GHZ LOW CURRENT AMPLIFIER				EA				B	A	EP	0		0	0.0	
		REF: U201										1.000000					
...4.....	31323904	0103 IC ADP3309-3.3 LDO VOLT REG (SOT-23-5)				EA				B	A	EP	0		0	0.0	
		REF: U102										1.000000					
...4.....	31323906	0104 IC KM616V1000 SRAM 3.3V 85NS TSOP				EA				B	A	EP	0		0	0.0	
		REF: U104										1.000000					
...4.....	31323915	0105 IC ASIC PCIC (TQFP-100)				EA				B	A	EP	0		0	0.0	
		REF: U401			1							1.000000					







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						EFF	DATE	PENDING	CATG	TOTAL	REQD	BILL	OPER	KIT	LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
			2		00040					QTY:		1				
...4.....	47CJ0180	0123 RES CHIP 18 OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R224								4.000000						
		REF: R234														
		REF: R223														
		REF: R277														
...4.....	47CJ0183	0125 RES CHIP 18K OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R501								2.000000						
		REF: R504														
...4.....	47CJ0202	0126 RES CHIP 2K OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R246								4.000000						
		REF: R249														
		REF: R251														
		REF: R255														
...4.....	47CJ0203	0127 RES CHIP,20K OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R268								2.000000						
		REF: R272														
...4.....	47CJ0242	0131 RES CHIP 2.4K OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R219								2.000000						
		REF: R256														
...4.....	47CJ0270	0132 RES CHIP 27 OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R233								2.000000						
		REF: R236														
...4.....	47CJ0271	0133 RES CHIP 270 OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R241								1.000000						
...4.....	47CJ0272	0134 RES CHIP 2.7K OHM 5% 1/16W 0402				EA			B	A	EP		0		0	0.0
		REF: R248								1.000000						



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ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
		2			00040					QTY:		1				
...4.....	47CJ0274	0135 RES CHIP 270K OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R273										3.000000				
		REF: R274														
		REF: R276														
...4.....	47CJ0334	0138 RES CHIP 330K OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R275										2.000000				
		REF: R335														
...4.....	47CJ0392	0139 RES CHIP 3.9K OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R200										2.000000				
		REF: R211														
...4.....	47CJ0393	0140 RES CHIP 39K 1/16W 5% 0402				EA				B	A	EP	0		0	0.0
		REF: R325										1.000000				
...4.....	47CJ0472	0141 RES CHIP 4.7K OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R258										5.000000				
		REF: R261														
		REF: R205														
		REF: R257														
		REF: R218														
...4.....	47CJ0473	0142 RES CHIP 47K OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R312										1.000000				
...4.....	47CJ0510	0144 RES CHIP 51 OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R235										2.000000				
		REF: R242														
...4.....	47CJ0560	0145 RES CHIP 56 OHM 5% 1/16W 0402				EA				B	A	EP	0		0	0.0
		REF: R201										1.000000				

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ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM EPF DATE	ABC PENDING	COMM CATG	CLASS CATG	TYPE TOTAL	ST REQD	PLNR BILL	BUYER OPER	MRP KIT	MPS LTO	YIELD SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A		Y	N	0.0	
		2			00040					QTY:		1				
...4.....	47CJ0682	0146 RES CHIP 6.8K OHM 5% 1/16W 0402				EA				B	A	EP	0	0	0.0	
		REF: R252										1.000000				
...4.....	47CJ0821	0149 RES CHIP 820 OHM 5% 1/16W 0402				EA				B	A	EP	0	0	0.0	
		REF: R244										2.000000				
		REF: R245														
...4.....	47CJ0913	0150 RES CHIP 91K OHM 5% 1/16W 0402				EA				B	A	EP	0	0	0.0	
		REF: R324										1.000000				
...4.....	48022384	0151 TRANSISTOR MMBT2222A NPN (SOT-23)				EA				B	A	EP	0	0	0.0	
		REF: Q502										2.000000				
		REF: Q503														
...4.....	48023143	0152 TRANSISTOR 2SC4251 NPN VHF SOT-2BIA				EA				B	A	EP	0	0	0.0	
		REF: Q200										3.000000				
		REF: Q201														
		REF: Q202														
...4.....	48023181	0153 TRANSISTOR NDS8434A P-CH FET SO-8				EA				B	A	EP	0	0	0.0	
		REF: Q501										1.000000				
...4.....	48090017	0154 TRANSISTOR RN4602-TR85L (PTR-B50)				EA				B	A	EP	0	0	0.0	
		REF: U307										1.000000				
...4.....	48223122	0156 DIODE 1SV232 TUNING VARACTOR				EA				B	A	EP	0	0	0.0	
		REF: CR201										2.000000				
		REF: CR202														
...4.....	48223167	0157 DIODE HSMS-2800 SCHOTTKY (SOT-23)				EA				B	A	EP	0	0	0.0	
		REF: CR200										1.000000				

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						EFF	DATE	PENDING	CATG	TOTAL	REQD	BILL	OFFER	KIT	LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD ORM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
		2			00040					QTY:		1				
...4.....	53023020	0159 THERMISTOR CHIP 22K 0603				EA			B	A	EP		0		0	0.0
											1.000000					
		REF: RT201														
...4.....	DA-01016582	0160 PCB ASSY PCMCIA CARD (MERLIN)				EA			P	A	EP		0		0	0.0
		2									0.000000					
...4.....	DC-17416582	0161 PANEL PCB PCMCIA CARD (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
...4.....	DDMP-17416582	0164 DESIGN DATA MFG.PKG PCMCIA CARD (MERLIN)				EA			P	A	EP		0		0	0.0
		2									0.000000					
...4.....	DDVP-17416582	0165 DESIGN DATA VEN.PKG PCMCIA CARD (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
...4.....	DF-17016582	0162 PC BOARD PCMCIA CARD (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
...4.....	DM-25615071	0076 EMI CHANNEL (MERLIN)				EA			P	A	EP		0		0	0.0
		2									0.000000					
...4.....	DS-01016582	0163 PCB ASSY PCMCIA CARD (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
...3.....	01016677	0002 LABEL EID (MERLIN)				EA			B	A	EP		0		0	0.0
		1									1.000000					
...4.....	25015435	0003 LABEL BLANK EID (MERLIN)				EA			B	A	EP		0		0	0.0
		1									1.000000					
...4.....	DA-01016677	0001 LABEL EID (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
...4.....	DM-25015435	0004 LABEL BLANK EID (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
...4.....	DP-01016677	0002 LABEL EID (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					

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						EFF	DATE	PENDING	CATG	TOTAL	REQD	BILL	OPER	KIT	LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
			2		00040					QTY:		1				
..3.....	14215025	0003 END BRACKET (MERLIN)				EA			B	A	EP		0		0	0.0
		1									1.000000					
..3.....	28315064	0005 EMI GASKET TOP (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	28315065	0007 EMI GASKET BOTTOM (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	28315066	0009 EMI GASKET FRONT (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	28315068	0011 EMI GASKET BOTTOM RIGHT (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	28315069	0013 EMI GASKET BOTTOM MMCK (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	28523002	0015 SCREW M2 X 3MM MACHINE FLAT HEAD				EA			B	A	EP		0		0	0.0
											2.000000					
..3.....	31015019	0016 INSULATOR BOTTOM SHIELD (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	31015020	0018 INSULATOR TOP SHIELD (MERLIN)				EA			B	A	EP		0		0	0.0
		2									1.000000					
..3.....	DA-01016632	0004 PCB MECH. ASSY (MERLIN)				EA			P	A	EP		0		0	0.0
		1									0.000000					
..3.....	DM-14215025	0004 END BRACKET (ROADRUNNER)				EA			P	A	EP		0		0	0.0
		1									0.000000					
..3.....	DM-28315064	0006 EMI GASKET TOP (MERLIN)				EA			P	A	EP		0		0	0.0
		2									0.000000					
..3.....	DM-28315065	0008 EMI GASKET BOTTOM (MERLIN)				EA			P	A	EP		0		0	0.0
		2									0.000000					

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ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0	
		2			00040					QTY:		1					
..3.....	DM-28315066	0010 EMI GASKET FRONT (MERLIN)				EA				P	A	EP	0		0	0.0	
		2										0.000000					
..3.....	DM-28315068	0012 EMI GASKET BOTTOM RIGHT (MERLIN)				EA				P	A	EP	0		0	0.0	
		2										0.000000					
..3.....	DM-28315069	0014 EMI GASKET BOTTOM MCK (MERLIN)				EA				P	A	EP	0		0	0.0	
		2										0.000000					
..3.....	DM-31015019	0017 INSULATOR BOTTOM SHIELD (MERLIN)				EA				P	A	EP	0		0	0.0	
		2										0.000000					
..3.....	DM-31015020	0019 INSULATOR TOP SHIELD (MERLIN)				EA				P	A	EP	0		0	0.0	
		2										0.000000					
..3.....	DP-01016632	0004 PCB MECH. ASSY (MERLIN)				EA				P	A	EP	0		0	0.0	
		1										0.000000					
..3.....	STP-01016486	0021 S/W TEST PLAN PCB ASSY (MODEM) EXPEDITE				EA				P	A	EP	0		0	0.0	
		3, 00044										0.000000					
..2.....	01016633	0008 TOP COVER ASSY (MERLIN)				EA				M	A	EP	0		0	0.0	
		1										1.000000					
..3.....	14223001	0002 COVER TOP, MERLIN				EA				B	A	EP	0		0	0.0	
												1.000000					
..3.....	28315070	0005 GASKET CONDUCTIVE ADHESIVE TOP 2 (MERLIN)				EA				B	A	EP	0		0	0.0	
		1										1.000000					
..3.....	70023001	0007 BRACKET 68 PIN CONNECTOR ADAPTOR				EA				B	A	EP	0		0	0.0	
												1.000000					
..3.....	DA-01016633	0001 TOP COVER ASSY (MERLIN)				EA				P	A	EP	0		0	0.0	
		1										0.000000					
..3.....	DM-28315070	0006 GASKET CONDUCTIVE ADHESIVE TOP 2				EA				P	A	EP	0		0	0.0	
		1										0.000000					

PDXIB1

INDENTED BILL OF MATERIALS  
 DATES: ALL

BY COMPONENT ID

ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM	ABC	COMM	CLASS	TYPE	ST	PLNR	BUYER	MRP	MPS	YIELD
						EFF	DATE	PENDING	CATG	TOTAL	REQD	BILL	OPER	KIT	LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
		2			00040					QTY:		1				
..3.....	DP-01016633	0001 TOP COVER ASSY (MERLIN)				EA				P	A	EP	0		0	0.0
		1										0.000000				
.2.....	01016634	0010 BOTTOM COVER ASSY (MERLIN)				EA				M	A	EP	0		0	0.0
		1										1.000000				
..3.....	14223002	0001 COVER BOTTOM, MERLIN				EA				B	A	EP	0		0	0.0
												1.000000				
..3.....	28315061	0002 GASKET CONDUCTIVE ADHESIVE BOTTOM				EA				B	A	EP	0		0	0.0
		1										1.000000				
..3.....	DA-01016634	0003 BOTTOM COVER ASSY (MERLIN)				EA				P	A	EP	0		0	0.0
		1										0.000000				
..3.....	DM-28315061	0003 GASKET CONDUCTIVE ADHESIVE BOTTOM				EA				P	A	EP	0		0	0.0
		1										0.000000				
.2.....	01016677	0011 LABEL EID (MERLIN)				EA				B	A	EP	0		0	0.0
		1										1.000000				
..3.....	25015435	0003 LABEL BLANK EID (MERLIN)				EA				B	A	EP	0		0	0.0
		1										1.000000				
..3.....	DA-01016677	0001 LABEL EID (MERLIN)				EA				P	A	EP	0		0	0.0
		1										0.000000				
..3.....	DM-25015435	0004 LABEL BLANK EID (MERLIN)				EA				P	A	EP	0		0	0.0
		1										0.000000				
..3.....	DP-01016677	0002 LABEL EID (MERLIN)				EA				P	A	EP	0		0	0.0
		1										0.000000				
.2.....	01016864	0012 LABEL ASSY TOP COVER (MERLIN CDPD OEM)				EA				M	A	EP	0		0	0.0
		1			00040							1.000000				
..3.....	25015433	0006 LABEL TOP COVER (MERLIN)				EA				B	A	EP	0		0	0.0
		1										1.000000				

PDXIB1

INDENTED BILL OF MATERIALS  
 DATES: ALL

BY COMPONENT ID

ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM	ABC	COMM	CLASS	TYPE	ST	PLNR	BUYER	MRP	MPS	YIELD
						EPF	DATE	PENDING	CATG	TOTAL	REQD	BILL	OPER	KIT	LTO	SCRAP
ASM: 649496	00265 7	MERLIN CDPD OEM (SYMBOL TECH)				EA	C	6494		M	A			Y	N	0.0
		2			00040					QTY:		1				
.3.....	AW-01016864	0002 LABEL ASSY TOP COVER (MERLIN CDPD OEM)				EA				P	A	EP		0	0	0.0
		1			00040							0.000000				
.3.....	DA-01016864	0002 LABEL ASSY TOP COVER (MERLIN CDPD OEM)				EA				P	A	EP		0	0	0.0
		1			00040							0.000000				
.3.....	DM-25015433	0010 LABEL TOP COVER (MERLIN)				EA				P	A	EP		0	0	0.0
		1										0.000000				
.2.....	01016865	0014 LABEL ASSY BOTTOM COVER MERLIN CDPD OEM				EA				M	A	EP		0	0	0.0
		2			00040							1.000000				
.3.....	25015434	0006 LABEL BOTTOM COVER (MERLIN)				EA				B	A	EP		0	0	0.0
		1										1.000000				
.3.....	AW-01016865	0002 LABEL ASSY BOTTOM COVER MERLIN CDPD OEM				EA				P	A	EP		0	0	0.0
		1			00040							0.000000				
.3.....	DA-01016865	0002 LABEL ASSY BOTTOM COVER MERLIN CDPD OEM				EA				P	A	EP		0	0	0.0
		1			00040							0.000000				
.3.....	DM-25015434	0010 LABEL BOTTOM COVER (MERLIN)				EA				P	A	EP		0	0	0.0
		1										0.000000				
.2.....	14623039	0016 BAG, BUBBLE WRAP (MERLIN)				EA				B	A	EP		0	0	0.0
												1.000000				
.2.....	20416419	0018 SW HEX FILE TR01-02				EA				B	A	EP		0	0	0.0
												1.000000				
.2.....	DA-01016863	0002 PC CARD MODULE (MERLIN CDPD OEM)				EA				P	A	EP		0	0	0.0
												0.000000				
.2.....	TF-01016863	0004 PC CARD MODULE (MERLIN CDPD OEM)				EA				P	A	EP		0	0	0.0
												0.000000				
1.....	01016879	0004 BOX MASTER CARTON (OEM)				EA				M	A	EP		0	0	0.0
		1			00040							1.000000				

FDXIB1

INDENTED BILL OF MATERIALS  
 DATES: ALL

BY COMPONENT ID

ASSEMBLY ID LEVEL	COMPONENT ID	DESCRIPTION START END	DWG	SIZE	ECN	UM	ABC	COMM	CLASS	TYPE	ST	PLNR	BUYER	MRP	MPS	YIELD
-----																
ASM: 649496 00265 7																
MERLIN CDPD OEM (SYMBOL TECH)																
2 00040																
QTY: 1																
-----																
.2.....	14323029	0004 BOX CARTON OEM 100 PCS BULK				EA	C	6494		M	A			Y	N	0.0
0.010000																
.2.....	DA-01016495	0002 BOX MASTER CARTON (MINSTREL AND SAGE)				EA				P	A					0.0
2 0.000000																

1 ASSEMBLIES PRINTED  
 0 COMPONENTS PRINTED WITH SHORTAGES





**Test Procedure**  
**for**  
**PC Card Module**

TP- 01016602

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	<b>DOCUMENT NO.:</b> TP-01016602	<b>SHEET:</b> 1 of 15	<b>REV:</b> 1



**REVISION HISTORY**

REV#	ER/C#	EFF. DATE	DESCRIPTION	PREPARED	APPROVED
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1		April 15, 1999	Modified for PC Card	G. May	

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### 1. INTRODUCTION

This document describes the manufacturing tests and alignments required for the PC Card Module (01016602).

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## 2. FIRMWARE UPLOAD

### 2.1 Description

The bootstrap loader will be programmed in the FLASH before they are placed on the board. The product software will be programmed at this point using the ENGPROG utility. It is necessary to use ENGPROG to program the units rather than programming the complete program in FLASH because ENGPROG is used to program the serial numbers. All PC Card modules will be programmed with the same firmware. The personality of the modem is set in the automated test by changing a parameter. The firmware upload takes approximately 1 minute per PC Card.

### 2.2 Equipment

Personal Computer or Notebook PC with a PC Card (PCMCIA) slot

Novatel Wireless supplied Engprog program and .cfg file

Novatel Wireless supplied .inf file

### 2.3 Procedure

1. Insert the PC Card into the PC's PC Card slot. If this is the first time a Novatel Wireless PC Card has been used on the PC; insert the disk with the .inf file and configure the PC to use the driver on the floppy disk.
2. Go to the directory with the programming software and product software. Type the command:  
*engprog -F product.cfg*  
where product.cfg is the name of the configuration file. The configuration file may need to be changed depending on the COM port used and the speed of the COM port.
3. ENGPROG will respond with :  
*Press Enter or Escape to continue*
4. Press the ENTER key.
5. ENGPROG will respond with a default EID. Enter the appropriate EID and press enter.
6. ENGPROG will respond with status messages and dots (...) when it is programming.
7. If on completion there are no error codes and the response is "device programming complete" then the module is properly programmed. ENGPROG is then ready to program the next module. Do not hit ESCAPE if you wish to program another module. Remove the module, insert a new module and start at step 3.

For more information on ENGPROG refer to the document NRM Series Flash Blaster User Guide.

### 2.4 Limits

ENGPROG will generate error codes if the programming has failed. Record the error code if present.

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### 3. AUTOMATED ALIGNMENT AND TEST

The automated test uses software supplied by Novatel Wireless. The description of the hardware setup and test procedure is included below. The automated test and alignment takes approximately 5 minutes per module.

#### 3.1 Equipment

The following pieces of test equipment are necessary for performing the alignment and manufacturing tests of the PC Card Module.

Description	Qty	Part Number	Manufacturer	Alternate Part Number	Alternate Manufacturer
RF Signal Generator	1	HP-8656B	Hewlett Packard		
Power Meter	1	HP-8901B	Hewlett Packard	HP-437B*	Hewlett Packard
Modulation Analyzer		HP-8901B	Hewlett Packard	HP-8901A*	Hewlett Packard
BERT Jig (New)	1		Novatel		
Power Sensor	1	HP-8482A	Hewlett Packard		
HPIB Card	1	HP-82335B	Hewlett Packard		
5 or 6 dB SMA Attenuator	1				
20 dB Attenuator	2				
10 dB Attenuator	1				
IEEE-488 bus cables	3				
Serial/power cable	1		Novatel		
			Novatel		
Power supply (6V, 1 Amp)	1				
Isolator	1	Si-30	Nippon Microwave Co.		
Power Splitter	1	15542	Mini Circuits		
Dual Directional Coupler	1	HP 775D	Hewlett Packard		
50 ohm Coax terminator	1	HP 908A	Hewlett Packard	Any 50 ohm terminator	
Banana Jack cable	2				
Banana Jack / alligator clip cable	2				
Digital Multimeter	1	HP 3784A	Hewlett Packard		
N- type Cables	2				
SMA type cable	1				
BNC type cable	2				
PC	1				
PC extender card	1	PCCextend 100	SYCARD		

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			Technology		
PC Card Bay	1	PCMRDWR	Linksys		
SMA to N adapter	1				

\* An HP-8901B Modulation Analyzer contains a power sensor input and can be used for accurate power measurements. Extra components may be required if these two pieces of equipment are used.

### 3.2 Test Description

The following tests are performed in the automated test stage:

- RSSI calibration
- Transmitter power level calibration
- Transmit modulation gain calibration
- TCXO Calibration
- RSSI accuracy
- Receiver RF sensitivity
- Transmitter frequency error
- Current consumption

### 3.3 Hardware Configuration

The hardware configuration is shown below.

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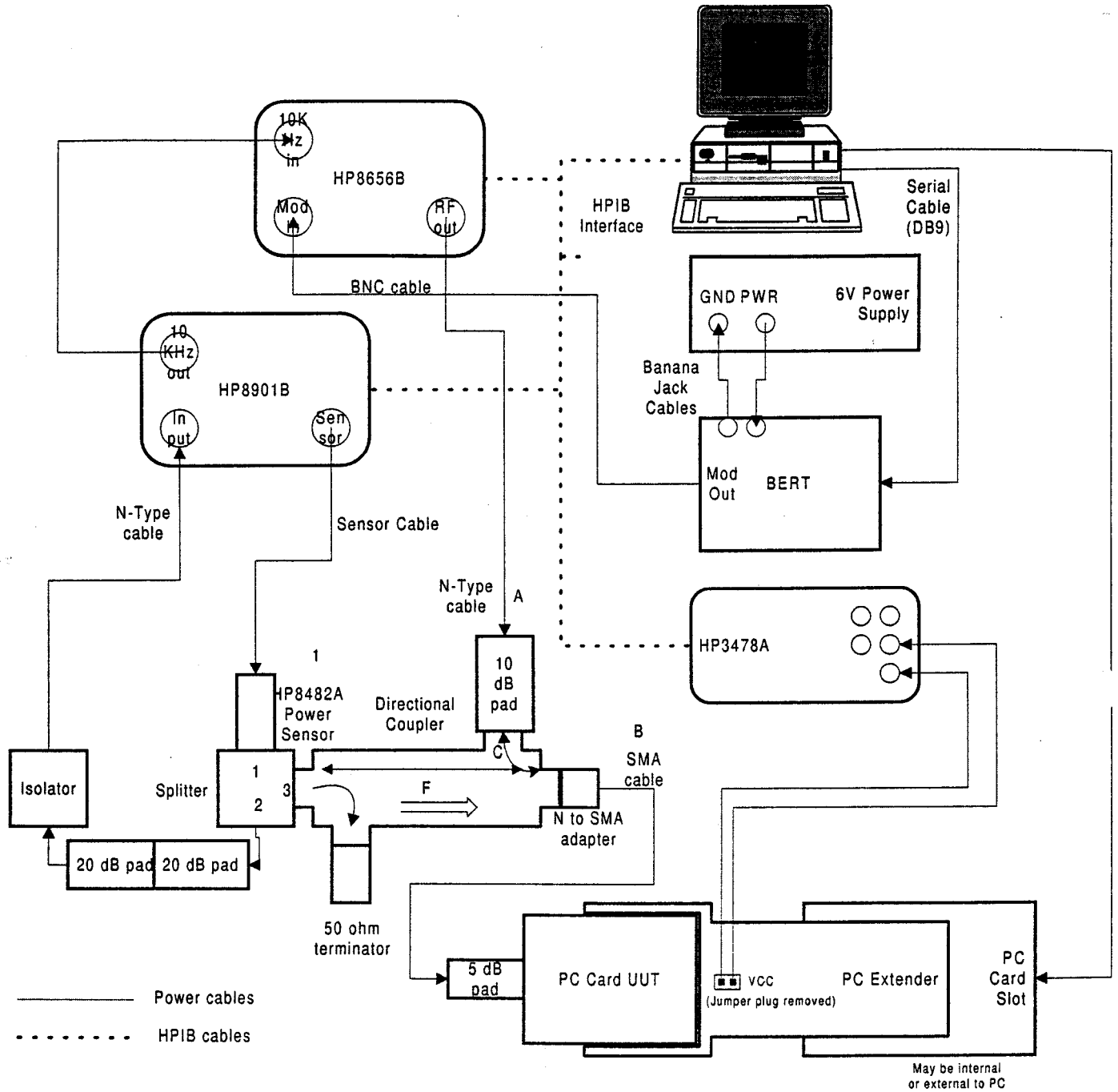


Figure 3: Equipment configuration for automated test

### 3.3.1 BERT Jig

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The BERT jig is used to perform the Receive Sensitivity test. There is a 26 pin cable which is not connected. The BNC Mod Out should be connected to the External Modulation input of the signal generator. The DB-9 connector should be connected with a 9 pin cable to the COM1 port of a PC. The GND banana jack should be connected to the GND of the power supply. The PWR banana jack should be connected to the PWR of the power supply.

### 3.4 Software Configuration

The software is configured using configuration files which saves the need for recompiling when equipment or test limits are changed. The format of the test configuration file is shown below.

TESTNAME  
 test on/off  
 number of channels  
 channel values list  
 begin level value, end level value, intermediate level value, step value  
 initial value filename  
 upper measlimit, lower measlimit  
 upper dpotlimit array - for rssi limits = 2.5\*x +110 +upper measlimit  
 lower dpotlimit array - for rssi limits = 2.5\*x +110 - lower measlimit  
 accuracy - for tcxo,txmcal&powcal-tune meas to +/- (upmeslim-lowmeaslim)\*acc/200  
 relative tolerance allowed - for rssi test only or current temp in celcius for tempcalibration  
 debug - 1 means turn debug info on, 0 means turn it off  
 end of parameters indicator

The format of the equipment configuration file is shown below.

EQUIPNAME  
 equipment type  
 address  
 calibration factor 1  
 calibration factor 2

For example:

SIGGEN  
 hp8656b  
 707  
 2  
 .002

The equipment name is the name used to identify the piece of equipment. The equipment type is the part number of the equipment. Valid part numbers are given in section 2. The address is the HPiB address of the equipment. The calibration factors are used to calibrate out deviations in the equipment and cable losses. This should be done before running the tests. The calibration factors are different for each piece of equipment. The table below shows the assignments.

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Equipment	Cal factor 1	Units	Cal factor 2	Units
Signal Generator	RF Amplitude	dB	RF Frequency	MHz
Power Meter*	RF Power	dB		
Audio Analyzer	Amplitude	V	Frequency	KHz
Modulation Analyzer	Frequency			
Digital Transmission Analyzer				
Switch Control Unit				
Digital Multimeter	Current of test jig for Vespa testing, 0 for PC Card testing.	A		

\* If the 8901B is used as a power meter then the cal factors have to be set up under the Power Meter configuration

### 3.5 Calibration of Test Stack

After the individual pieces of equipment are calibrated it is necessary to calibrate out cable losses in the test stack. The results of the calibration are entered in the equip.cfg file. Each piece of equipment has two calibration factors. The table below gives a description of each calibration factor for each piece of equipment.

Equip Signal Generator	Cal Factor 1 Amplitude in dB - gives the total loss from the antenna port to the signal generator RF output, includes losses in cables and attenuators	Cal Factor 2 Frequency in KHz - the difference between the signal generator frequency and the actual measured frequency.
Modulation Analyzer		Frequency in Hz - the difference between the modulation analyzer frequency and the actual input frequency.
Power Meter	Amplitude in dB - gives the total loss from the antenna port to the power meter sensor input, includes losses in cables and attenuators	
Digital Multimeter	PC Card current	

The basic assumption is that the signal generator power output is accurate. The specification is +/- 1dB, but the results from calibration of the test stack in Calgary showed the HP sig gen to be within 0.5 dB. Any errors in this assumption will effect receive sensitivity numbers. If there is any doubt about the signal generator's absolute power or linearity, it should be sent out to HP to obtain calibration data and then the RF levels can be adjusted accordingly.

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### 3.5.1 Method

1. Establish a reference by directly connecting the 8482A power sensor to the type N connector on the signal generator. Set the signal generator to the mid band of the AMPS cellular receive frequency of 881 MHz. Set the signal generator to +15 dBm. This is out of the calibrated range of the signal generator, but it will not effect the measurement, because the measurement will be relative not absolute. Using a higher RF level on the signal generator will improve the accuracy, of measurement taken with the HP 8482A power sensor, because it is most linear in the range of +20 dBm to +10 dBm. To zero the reference, use the "rel" function on the modulation analyzer.
2. First measure the N-type cable (A) and the directional coupler in the RX path by inserting it between the signal generator and the power sensor. All other terminals on the directional coupler should be terminated with 50 ohm. Measure the attenuation. The attenuation can be read directly from the modulation analyzer display, because it is in "rel" mode.
3. Remove the directional coupler and connect the SMA cable (B) and the 5 dB attenuator. By using a blank PCB with a coaxial SMA pig tail, the test jig cables and barrel connector can be factored into the total attenuation of the receive path. Measure the attenuation of the SMA cable and the test jig cables.
4. The total attenuation in the receive path is A+B+C.
5. The transmit path attenuation is measured in the same manner but with the signal generator set to 836 MHz. Make sure any unused terminals are terminated with 50 ohm.
6. The DMM should be checked as follows. The test jig is connected and power is applied. No unit is inserted in the PC Card slot. The power switch is moved to the ON position. The current on the DMM should be 0.0 Amps, and this is recorded and entered in the equip.cfg file in Amps.

### 3.6 Running The Test And Alignment Program

Files needed to run the program are stored in the directory c:\6832test. The files should be copied to the network as the directory the program is run from is the directory used to store results. The program should be started once each day or every time the type of module being assembled is changed. The files are:

- a.bat**: batch file which runs the test with the necessary configuration files.
- nts.exe**: the executable program file
- equip.cfg**: equipment configuration file
- test.cfg**: test configuration file

The following steps are taken to run the program:

1. Type the command 'a'
2. Select a number for the unit configuration
3. Plug unit in to PC Card slot
4. Plug antenna connector in to unit

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- 5. Press Enter
- 6. Test will run and display tests which have failed
- 7. Repeat steps 3 through 6 for each unit

### 3.7 Output Files

The NTS system produces two types of output files. The first is a file for each unit tested with results of each test and alignment. The format of this file is xxxxxx.out, where xxxxxx is the last 6 digits (hex) of the serial number of the unit. The second is a file for each test with results for each unit tested. The format of the second file is xxxxxx.txt where xxxxxx is the name of the test or calibration performed.

### 3.8 Error Messages

#### 3.8.1 Equipment Failures

- 100: Unknown error
- 101: Invalid selector code or device address
- 102: Command parameter out of range
- 103: Timeout error
- 104: HPIB card is not active controller

Result: Test will exit for this unit for any of these failures.

#### 3.8.2 NRM Fatal Errors

##### 200: Power Up Failure

Description: The unit is not responding with a '9' on power up. This can be caused by a number of things. Serial communications may not be working, which is not likely if the unit has been programmed. The more likely cause of the failure is the VHF synthesizer not locked. A third possibility is that the module has been set to communicate at a different baud rate than the 9600 or 19200 the test program uses.

Result: Test will exit for this unit

##### 201: Serial Communications Failure

Description: The unit does not respond to a serial communications command sent to the unit. The test should be repeated for this unit. If the problem persists debugging is necessary.

Result: Test will exit for this unit

##### 202: FSU lock failure

Description: One of the synthesizers is not locked due to a problem on the board

Result: Test will exit for this unit

##### 203: NVM Failure

Description: The module is unable to store the calibration factors in NVM, likely due to a problem with the serial EEPROM on the board

Result: Test will exit for this unit

#### 3.8.3 Test or Alignment Failures

##### 300: RSSI Calibration Failure

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- 301: Rx Demod Calibration Failure
- 302: Tx Power Calibration Failure
- 303: Tx Modulation Calibration Failure
- 304: RSSI Test Failure
- 305: Rx Sensitivity Test Failure
- 306: Tx Freq Test Failure
- 307: Tx Power Test
- 308: Rx Demod Test Failure
- 309: Tx Modulation Test
- 310: Current Test Failure

Result: The results of the test will be recorded as usual.

#### 4. REGISTRATION TEST

The functional test consists of connecting the unit under test to a CDPD base station emulator, and performing a registration procedure. Successful registration indicates that the unit is indeed functional.

##### 4.1 Equipment Required

1. IFR-uCell-100 with CDPD option
2. PC or notebook PC with a type II PC Card slot and with terminal utility (Hyperterminal or Procomm Communications)
3. MMCX interface cable
4. PC Card (UUT) to be tested.

The equipment will be wired as indicated:

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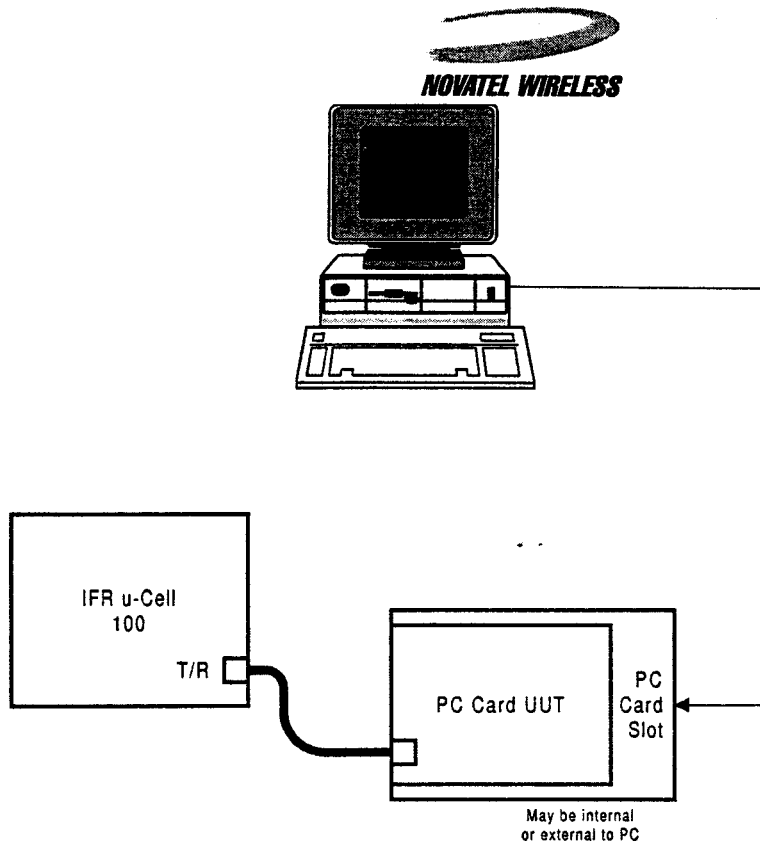


Figure 9.2.1. Functional Test Connection Diagram.

## 4.2 Test Procedure

The IFR should be set-up as follows: (This set-up will only have to be performed once at the start of testing and not before each unit is tested)

1. Power up the IFR
2. From the Menu press 9 CDPD TESTS
3. Press 2 MANUAL. The settings for the MANUAL screen should be:

SEND MESSAGE	ICMP PING	RF LEVEL	-40
CHANNEL	991	MAX POWER	2
TEST MODE	BURST	POWER PRODUCT	39
CDPD SPEC	1.1	PING MODE	AUTOMATIC

4. Press CABLE
5. Attach the cable to be used between the T/R connector and the CABLE TEST connector
6. Press START
7. Press MANUAL, and add 0.5 dB to the measured cable loss to compensate for the NRM antenna cable
8. Insert the PC Card into the PC Card slot and attach the cable to the PC Card.
9. Start the terminal session to the PC Card.
10. Press START on the IFR. Within 30 seconds the IFR should indicate that registration has taken place. Once the unit responds with an ABCDE on the terminal the unit passes. Record a PASS/FAIL for the registration test
11. Record the modulation index for the unit. Unit passed if between 0.45 and 0.54. Record the Frequency error for the unit.

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- 12. Check that the EID on the label matches the EID displayed on the IFR.
  - 13. Perform test 5. **RSSI Test**
  - 14. Close the terminal session to the PC Card
- Repeat steps 8 to 11 for each module tested.

## 5. RSSI TEST

The purpose of this test is to check the RSSI to confirm that the antenna connector and antenna matching components were properly placed.

### 5.1 Equipment Required

- 1. IFR-uCell-100 with CDPD option
- 2. PC or notebook PC with a type II PC Card slot and with terminal utility (Hyperterminal or Procomm Communications)
- 3. MMCX interface cable
- 4. PC Card (UUT) to be tested.

### 5.2 Test Procedure

While still connected to the IFR enter the following commands in the terminal:  
*ats202?*

Record the result. The unit has passed if the result is between 62 and 66. Enter the command *ath4* and press the STOP button on the IFR.

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